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File: DWPI

Jan 6, 1998

DERWENT-ACC-NO: 1998-116280

DERWENT-WEEK: 199811

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TITLE: Photosensitive composition - containing polymer with aliphatic side chain,
and used in the manufacture of a semiconductor device

PATENT-ASSIGNEE:

ASSIGNEE

CODE

TOSHIBA KK

TOKE

PRIORITY-DATA:

1996JP-0156962

June 18, 1996

PATENT-FAMILY:

PUB-NO

PUB-DATE

LANGUAGE

PAGES

MAIN-IPC

JP 10003169 A

January 6, 1998

N/A

014

G03F007/039

APPLICATION-DATA:

PUB-NO

APPL-DESCRIPTOR

APPL-NO

APPL-NO

JP10003169A

June 18, 1996

1996JP-0156962

N/A

INT-CL (IPC): C08L 33/04; C08L 101/00; C09D 133/04; G03F 7/004; G03F 7/039; H01L 21/027

ABSTRACTED-PUB-NO: JP10003169A

BASIC-ABSTRACT:

Photosensitive compsn. contains a polymer cpd. which has a side chain with alicyclic construction to which at least one kind of subst. gp. of OH gp. and NO2 gp. is introduced or a heterocyclic construction to which S with two O being bonded is introduced.

USE - The compsn. is used for resist material used for fine processing in manufacture of a semiconductor element.

ADVANTAGE - The photosensitive compsn. for alkali development can form a resist pattern which has improved resolution, sensitivity, and dry etching resistance and also which does not cause any problems such as generation of cracking and separation from a substrate. Thereby, the photosensitive compsn. is effective for fine processing in manufacture of a high integrated semiconductor device.

CHOSEN-DRAWING: Dwg.0/0

TITLE-TERMS: PHOTSENSITISER COMPOSITION CONTAIN POLYMER ALIPHATIC SIDE CHAIN
MANUFACTURE SEMICONDUCTOR DEVICE

DERWENT-CLASS: A89 G06 L03 P84 U11

CPI-CODES: A08-M08; A12-E07C; A12-L02B2; G06-D06; G06-F03C; G06-F03D; L04-C05;

EPI-CODES: U11-A06A;

ENHANCED-POLYMER-INDEXING:

Polymer Index [1.1] 018 ; P0000 ; L9999 L2391 ; L9999 L2108 L2095 ; M9999 M2108
M2095 Polymer Index [1.2] 018 ; ND01 ; Q9999 Q7476 Q7330 ; Q9999 Q8684 Q8673 Q8606
; Q9999 Q8673*R Q8606 ; B9999 B4580 B4568 ; B9999 B3769 B3758 B3747 ; B9999
B3849*R B3838 B3747 ; K9585 K9483 ; K9687 K9676 ; K9676*R ; K9712 K9676 ; K9416

SECONDARY-ACC-NO:

CPI Secondary Accession Numbers: C1998-038463

Non-CPI Secondary Accession Numbers: N1998-093192

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☐ 1. Document ID: JP 10003169 A

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21/027

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